

6-1761614-2 ✓ ACTIVE

STEP-Z

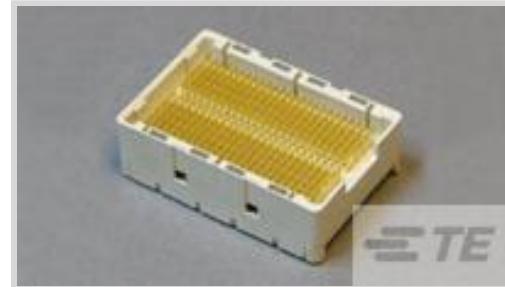
TE Internal #: 6-1761614-2

PCB Mount Header, Vertical, Board-to-Board, 200 Position, 1.3 mm [.051 in] Centerline, Partially Shrouded, Gold, Surface Mount - Solder Ball

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: **PCB Mount Header**

PCB Mount Orientation: **Vertical**

Connector System: **Board-to-Board**

Number of Positions: **200**

Number of Rows: **2**

Features

Product Type Features

| | |
|-----------------------------------|-----------------------|
| PCB Connector Assembly Type | PCB Mount Header |
| Connector System | Board-to-Board |
| Header Type | Partially Shrouded |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |

Configuration Features

| | |
|------------------------------|----------|
| Stackable | Yes |
| PCB Mount Orientation | Vertical |
| Number of Positions | 200 |
| Number of Rows | 2 |
| Board-to-Board Configuration | Parallel |

Electrical Characteristics

| | |
|---------------------------------------|---------|
| Dielectric Withstanding Voltage (Max) | 500 VAC |
| Insulation Resistance | 18 MΩ |
| Operating Voltage | 48 VAC |

Body Features

| | |
|-----------------------|---------|
| Primary Product Color | Natural |
|-----------------------|---------|

Contact Features

| | |
|--|--------------------------------|
| Contact Layout | Matrix |
| Mating Tab Width | 1 mm [.04 in] |
| Mating Tab Thickness | .2 mm [.008 in] |
| Contact Shape & Form | Dual Beam, Single Beam, Square |
| PCB Contact Termination Area Plating Material | Tin-Silver |
| Contact Base Material | Copper Alloy |
| Contact Mating Area Plating Material | Gold |
| Contact Mating Area Plating Material Thickness | .76 μ m [29.9212 μ in] |
| Contact Type | Tab |
| Contact Current Rating (Max) | 1 A |

Termination Features

| | |
|---------------------------|-----------------------------|
| Termination Method to PCB | Surface Mount - Solder Ball |
|---------------------------|-----------------------------|

Mechanical Attachment

| | |
|-------------------------|-------------|
| Mating Retention | With |
| Mating Alignment | Without |
| PCB Mount Retention | Without |
| PCB Mount Alignment | Without |
| Connector Mounting Type | Board Mount |

Housing Features

| | |
|--------------------|------------------|
| Centerline (Pitch) | 1.3 mm [.051 in] |
| Housing Material | Thermoplastic |

Dimensions

| | |
|-----------------------------|--------------------------------|
| Connector Height | 12.95 mm [.509 in] |
| Row-to-Row Spacing | 2 mm [.079 in] |
| Stack Height | 17 mm, 23 mm, 27 mm [1.063 in] |
| PCB Thickness (Recommended) | 1.57 mm [.8 in] |

Usage Conditions

| | |
|-----------------------------|--------------------------|
| Operating Temperature Range | 0 – 100 °C [32 – 212 °F] |
|-----------------------------|--------------------------|

Operation/Application

| | |
|--------------------------|----------------|
| Assembly Process Feature | None |
| Circuit Application | Power & Signal |

Industry Standards

UL Flammability Rating

UL 94V-0

Packaging Features

Packaging Quantity

25

Packaging Method

Tray

Product ComplianceFor compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU

Compliant

EU ELV Directive 2000/53/EC

Compliant

China RoHS 2 Directive MIIT Order No 32, 2016

No Restricted Materials Above Threshold

EU REACH Regulation (EC) No. 1907/2006

Current ECHA Candidate List: JUNE 2024 (241)
 Candidate List Declared Against: JUNE 2024 (241)
 Does not contain REACH SVHC

Halogen Content

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability

Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts

TE Part # 6-1761615-1
STEP-Z RCPT 11MM 200P LF ST



TE Part # 6-1761615-5
STEP-Z RCPT 15MM 200P LF ST



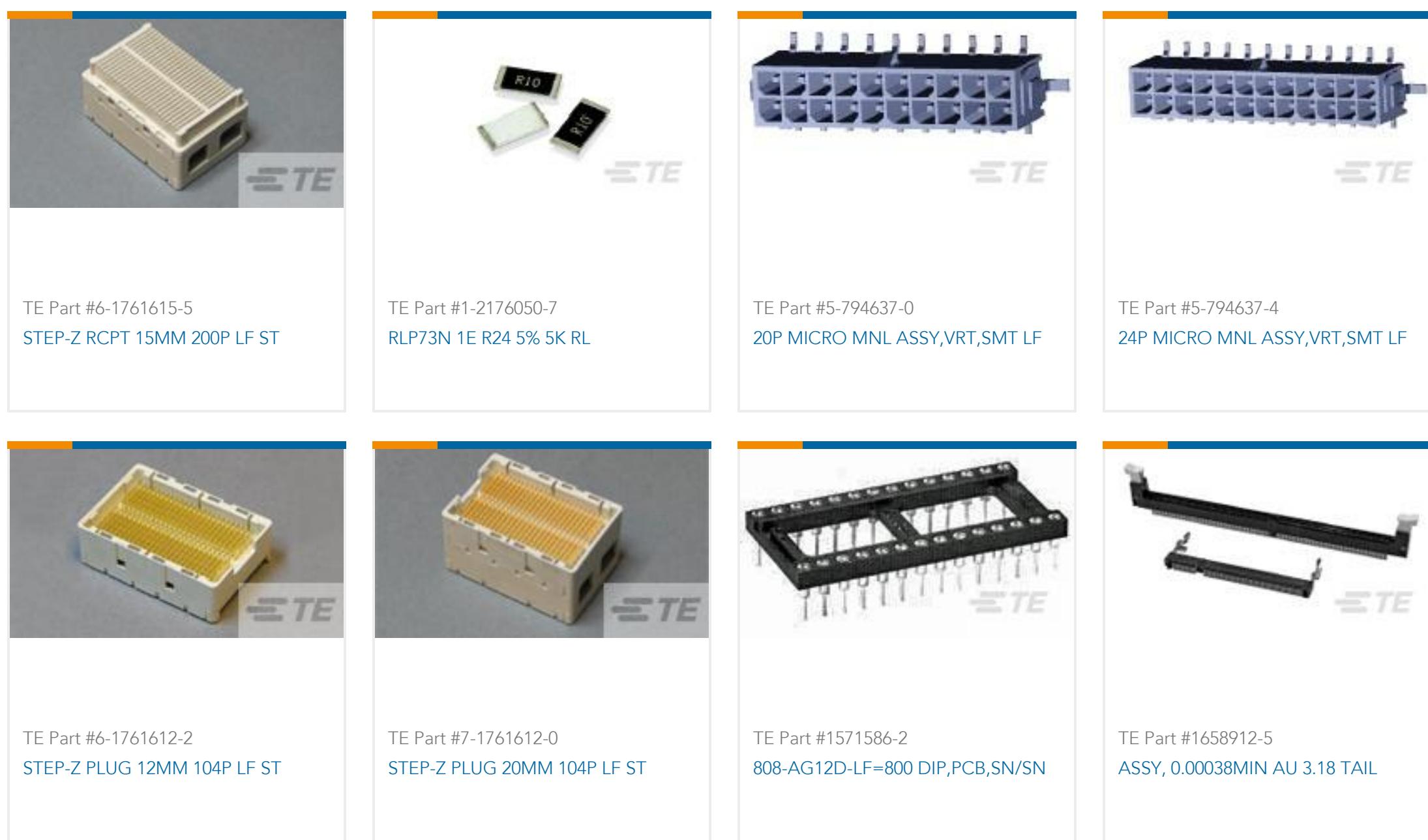
TE Part # 5-1761615-5
STEP-Z RCPT 05MM 200P LF ST



TE Part # 5-2007615-5
STEP-Z RCPT 05MM 200P LF HT



Customers Also Bought



Documents

Product Drawings

[STEP-Z PLUG 12MM 200P LF ST](#)

English

CAD Files

Customer View Model

[ENG_CVM_CVM_6-1761614-2_B.2d_dxf.zip](#)

English

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_6-1761614-2_B.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_6-1761614-2_B.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

STEP-Z Interconnection System

English

Product Specifications

Application Specification

English